

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-8 (canceled).

9. (New) A press-fit diode, comprising:

a diode chip;

a base contact for pressing the press-fit diode into a substrate, wherein the base contact is attached to the diode chip and forms a first terminal of the press-fit diode; and

a wire contact which forms a second terminal of the press-fit diode, wherein the wire contact is attached to the diode chip and is at least partially provide with a silver layer.

10. (New) The press-fit diode as recited in claim 9, wherein a section of the wire contact attached to the diode chip is not provided with the silver layer.

11. (New) The press-fit diode as recited in claim 10, wherein the base contact is not provided with a silver layer.

12. (New) The press-fit diode as recited in claim 10, wherein the wire contact further includes a nickel layer on which the silver layer is applied.

13. (New) A method for manufacturing a press-fit diode, comprising:

providing a diode chip;

providing a base contact configured for pressing the press-fit diode into a substrate, wherein the base contact forms a first terminal of the press-fit diode;

providing a wire contact which forms a second terminal of the press-fit diode, wherein the wire contact is at least partially provided with a silver layer; and

fixedly connecting the wire contact, the base contact, and the diode chip to one another.

14. (New) The method as recited in claim 13, wherein a section of the wire contact attached to the diode chip is not provided with the silver layer.

15. (New) The method as recited in claim 13, wherein the base contact is not provided with a silver layer.

16. (New) The method as recited in claim 14, wherein the base contact is not provided with a silver layer.

17. (New) The method as recited in claim 13, wherein the wire contact is made of copper, and wherein the wire contact is further provided with a nickel layer on which the silver layer is applied.

18. (New) The method as recited in claim 14, wherein the wire contact is made of copper, and wherein the wire contact is further provided with a nickel layer on which the silver layer is applied.